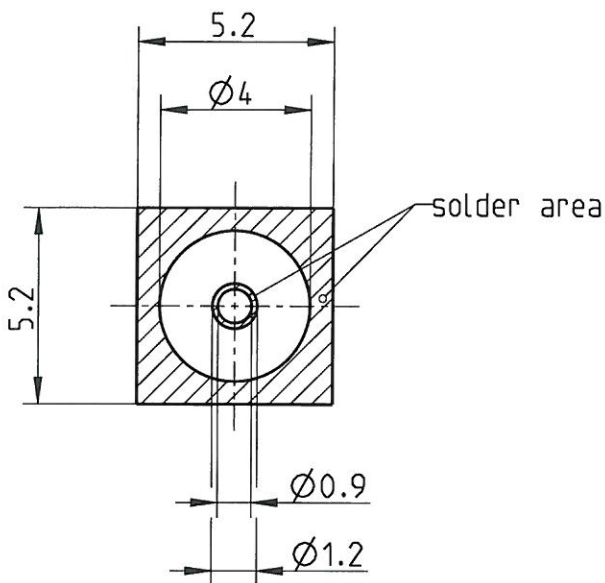


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Leiterplatten-LAYOUT  
PCB layout  
B 123



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: TCC\_BB\_05\_PC\_A4-Einzelteil  
Datei: AA-EINZELTEIL\_EDB.FRM  
Version: 1.0

-METRIC-

ISO-Projektion  
Methode E

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance <b>ISO 2768 RN 006-01</b> m-H dimensions <0,5 and symmetry		scale: 5:1	weight(g): surface(mm <sup>2</sup> ):
				material:	
		date name drawn 14.11.2005 A_Nobis check 30.11.05 [Signature] appr. 2/12/05 [Signature]		title: <b>Leiterplatten-LAYOUT PCB layout</b>	
		dimensioning incl. finish		part-no.: MB_123	
a00	05-0615	A_Nobis	15.11.2005	distribu- tion to:	FE AZ QSM RMT . X . . . .
rev. change-no name date				sheet: 1 of: 1	
				remarks: .	